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DESCRIPTION

METHOD OF MANUFACTURING MULTI-LAYER CIRCUIT BOARD

5 BACKGROUND OF THE INVENTION

1. FIELD OF THE INVENTION

The present invention relates to a method of manufacturing a multi-layer circuit board that has inner via-hole connection via conductive paste.

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2. DESCRIPTION OF THE RELATED ART

In recent years, as electronic devices are formed into smaller in size and higher in-density, a multi-layer circuit board has been strongly needed not only for industrial use but also for consumer products.

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To provide a multi-layer circuit board with high-density, microscopic and multi-layered circuit patterns have been developing. At the same time, a thin circuit board has also been needed.

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Such a multi-layer circuit board requires highly reliable interlayer connections in which circuit patterns formed on the layers are connected via inner via-holes. For example, Japanese Patent Unexamined Publication No. H06-268345 introduces a method of manufacturing a high-density circuit board that offers inner via-hole connections via conductive paste filled in via-holes.

Hereinafter will be described a conventional method of manufacturing a multi-layer circuit board, in particular, a four-layered circuit board.

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First, a description will be given on the manufacturing process of a double-sided circuit board that is the base of a four-layered circuit board.

Figs. 5A through 5F illustrate the manufacturing process of a